Title: Datasheet update for TMP112 Customer Contact: PCN Manager Dept: Quality Services	PCN Number: 20150420001				PCN Date:		04/22/2014	
Change Type: Assembly Site Assembly Process Data Sheet Wafer Bump Material Assembly Materials Part number change Wafer Bump Process Wafer Fab Materials Packing/Shipping/Labeling Test Site Wafer Fab Materials PCN Details PCN Details PCN Details Description of Change: Texas Instruments Incorporated is announcing an information only notification etc. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TMP112 SECSIFIOL MARCH 2009-REVISED AFRIL 2015 Wawkill.com Changes from Revision C (October 2014) to Revision D Page Changed MIN, TYP, and MAX values for the Temperature Accuracy (temperature error) parameter 5 Changed the Temperature Error at 25°C graph in the Typical Characteristics section 7 Changed the Temperature Error ws Temperature graph in the Typical Characteristics section 7 Changes from Revision B (June 2009) to Revision C Page Added Handling Rating table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Suppors section, and Mechanical, Packaging, and Orderable Information section, Device and Documentation Suppors section, and Mechanical, Packaging, and Orderable Information section, Device and Documentation Suppors section, and Mechanical, Packaging, and Orderable Information section, Device and Documentation Suppors section, and Mechanical, Packaging, and Orderable Information section, Device and Documentation Suppors section, and Mechanical, Packaging, and Orderable Information section, Device and Documentation Suppors section, and Mechanical, Packaging, and Orderable Information section, Device and Documentation Suppors section, and Mechanical, Packaging, and Orderable Information section, Device and Documentation Suppors section, and Mechanical, Packaging, and Orderable Information section, Device and Documentation Suppors section, and Mechanical, Packaging, and Orderable Information s	Title: Datasheet up	odate for TMP11	2					
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PCN Details Pescription of Change: Texas Instruments Incorporated is announcing an information only notification etc. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TMP112 SBOS4730_MARCH 2009_REVISED APRIL 2015 Changes from Revision C (October 2014) to Revision D Page Changed MIN, TYP, and MAX values for the Temperature Accuracy (temperature error) parameter Changed the Terquency from 2.85 to 3.4 MHz in the POWER SUPPLY section of the Electrical Characteristics table Changed the Temperature Error at 25°C graph in the Typical Characteristics section 7 Changes from Revision B (June 2009) to Revision C Page Added Handing Rating table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section Changed parameters in Timing Requirements Changed parameters in Timing Requirements Change Toe TMP112 SBOS473B SBOS473D These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/tmp112 Reason for Change: Changes to product identification resulting from this PCN: None. Product Affected:				4				
PCN Details Pescription of Change: Texas Instruments Incorporated is announcing an information only notification etc. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TMP112 ***SROS4730-MARCH 2009-REVISED APRIL 2015** ***Changes from Revision C (October 2014) to Revision D ***Changed MIN, TYP, and MAX values for the Temperature Accuracy (temperature error) parameter				╁┝				
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To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: None. Product Affected:	Changed the frequency from 2.85 to 3.4 MHz in the POWER SUPPLY section of the Electrical Characteristics table							
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	None.							
	Product Affected:							
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail			
USA	PCNAmericasContact@list.ti.com			
Europe	PCNEuropeContact@list.ti.com			
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